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O.I.P.E. YAC TC CH SCANNED Q.A. <i>Don</i>	PATENT DATE 
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PLICANTS Vishnu Agarwal
Garo Derderian
Gurtej Sandhu
Weimin Li

Methods for forming and integrated circuit structures containing ruthenium and tungsten containing 10.000

PTO-2040
12/89

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11-24-03 Formal Drawings (1 sm) set 1 6-8-00

<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS		CLAIMS ALLOWED	
	Sheets Dwg. 4	Figs. Dwg. 12	Print Fig. 88	Total Claims 47
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.	8/12/03 (Assistant Examiner)		NOTICE OF ALLOWANCE MAILED 08/12/03	
	David Nelms Supervisory Patent Examiner Technology Center 2800 8/03 (Date)		ISSUE FEE	
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S. Patent. No. _____	7/03 (Primary Examiner)		Amount Due \$60.50	Date Paid 7-03
<input type="checkbox"/> The terminal _____ months of this patent have been disclaimed.	7/03 (Legal Instruments Examiner)		ISSUE BATCH NUMBER	

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Drawing

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